

Liangbiao Chen

List of Publications by Year in descending order

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19
papers

173
citations

1040056

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19
all docs

19
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19
times ranked

254
citing authors

#	ARTICLE	IF	CITATIONS
1	Testing and Modeling of Board Level Reliability of WLCSP under UHAST Conditions. , 2021, , .		0
2	Die and Package Level Thermal and Thermal/Moisture Stresses in 3-D Packaging: Modeling and Characterization. Springer Series in Advanced Microelectronics, 2021, , 431-469.	0.3	0
3	An Arrhenius-type constitutive model to predict the deformation behavior of Sn0.3Ag0.7Cu under different temperature. Journal of Materials Science: Materials in Electronics, 2019, 30, 14611-14620.	2.2	7
4	Experimental and numerical study on dynamic mechanical behaviors of low-silver lead-free solder under combined compression-shear loadings. Journal of Materials Science: Materials in Electronics, 2019, 30, 18678-18685.	2.2	1
5	A Novel Interconnected Structure of Graphene-Carbon Nanotubes for the Application of Methane Adsorption. IEEE Sensors Journal, 2018, 18, 1555-1561.	4.7	5
6	A Review on Water Vapor Pressure Model for Moisture Permeable Materials Subjected to Rapid Heating. Applied Mechanics Reviews, 2018, 70, .	10.1	10
7	The Effects of Graphene Stacking on the Performance of Methane Sensor: A First-Principles Study on the Adsorption, Band Gap and Doping of Graphene. Sensors, 2018, 18, 422.	3.8	9
8	Modeling nonlinear moisture diffusion in inhomogeneous media. Microelectronics Reliability, 2017, 75, 162-170.	1.7	18
9	A Unified and Versatile Model Study for Moisture Diffusion. , 2017, , .		4
10	A First-Principle Theoretical Study of Mechanical and Electronic Properties in Graphene Single-Walled Carbon Nanotube Junctions. Materials, 2017, 10, 1300.	2.9	15
11	Design and adjustment of the graphene work function via size, modification, defects, and doping: a first-principle theory study. Nanoscale Research Letters, 2017, 12, 642.	5.7	28
12	Die and Package Level Thermal and Thermal/Moisture Stresses in 3D Packaging: Modeling and Characterization. Springer Series in Advanced Microelectronics, 2017, , 293-332.	0.3	6
13	Experimental study on the dynamic mechanical properties of titanium alloy after thermal oxidation. Applied Physics A: Materials Science and Processing, 2016, 122, 1.	2.3	7
14	Modeling of moisture over-saturation and vapor pressure in die-attach film for stacked-die chip scale packages. Journal of Materials Science: Materials in Electronics, 2016, 27, 481-488.	2.2	12
15	Effects of Vapor Pressure and Super-Hydrophobic Nanocomposite Coating on Microelectronics Reliability. Engineering, 2015, 1, 384-390.	6.7	10
16	A convectionâ€“diffusion porous media model for moisture transport in polymer composites: Model development and validation. Journal of Polymer Science, Part B: Polymer Physics, 2015, 53, 1440-1449.	2.1	18
17	An Insight to High Humidity-Caused Friction Modulation of Brake by Numerical Modeling of Dynamic Meniscus under Shearing. Lubricants, 2015, 3, 437-446.	2.9	5
18	LED's luminous flux lifetime prediction using a hybrid numerical approach. , 2015, , .		5

#	ARTICLE	IF	CITATIONS
19	Investigation of impact dynamics of roof bolting with passive friction control. International Journal of Rock Mechanics and Minings Sciences, 2014, 70, 559-568.	5.8	13